



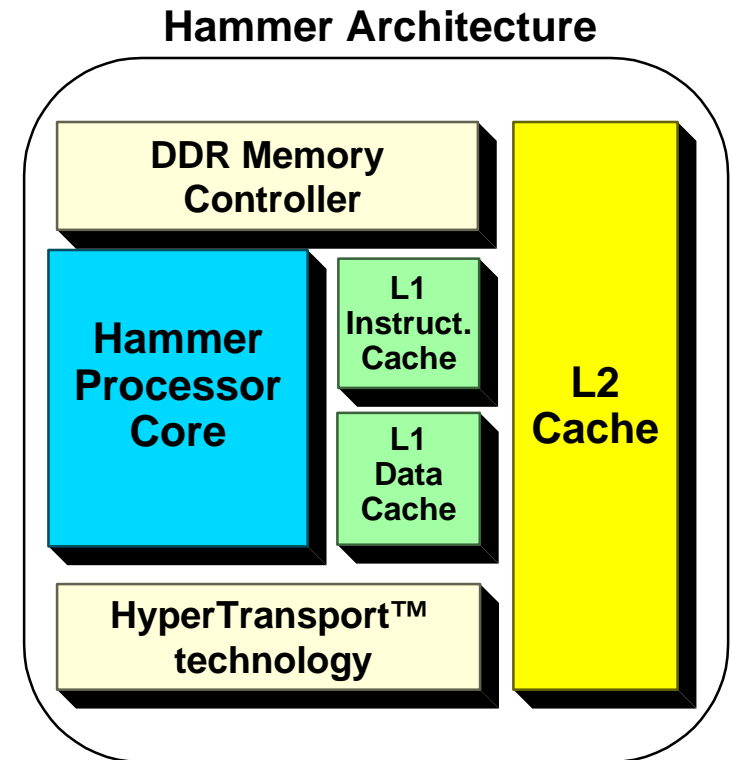
# The AMD Hammer Processor Core

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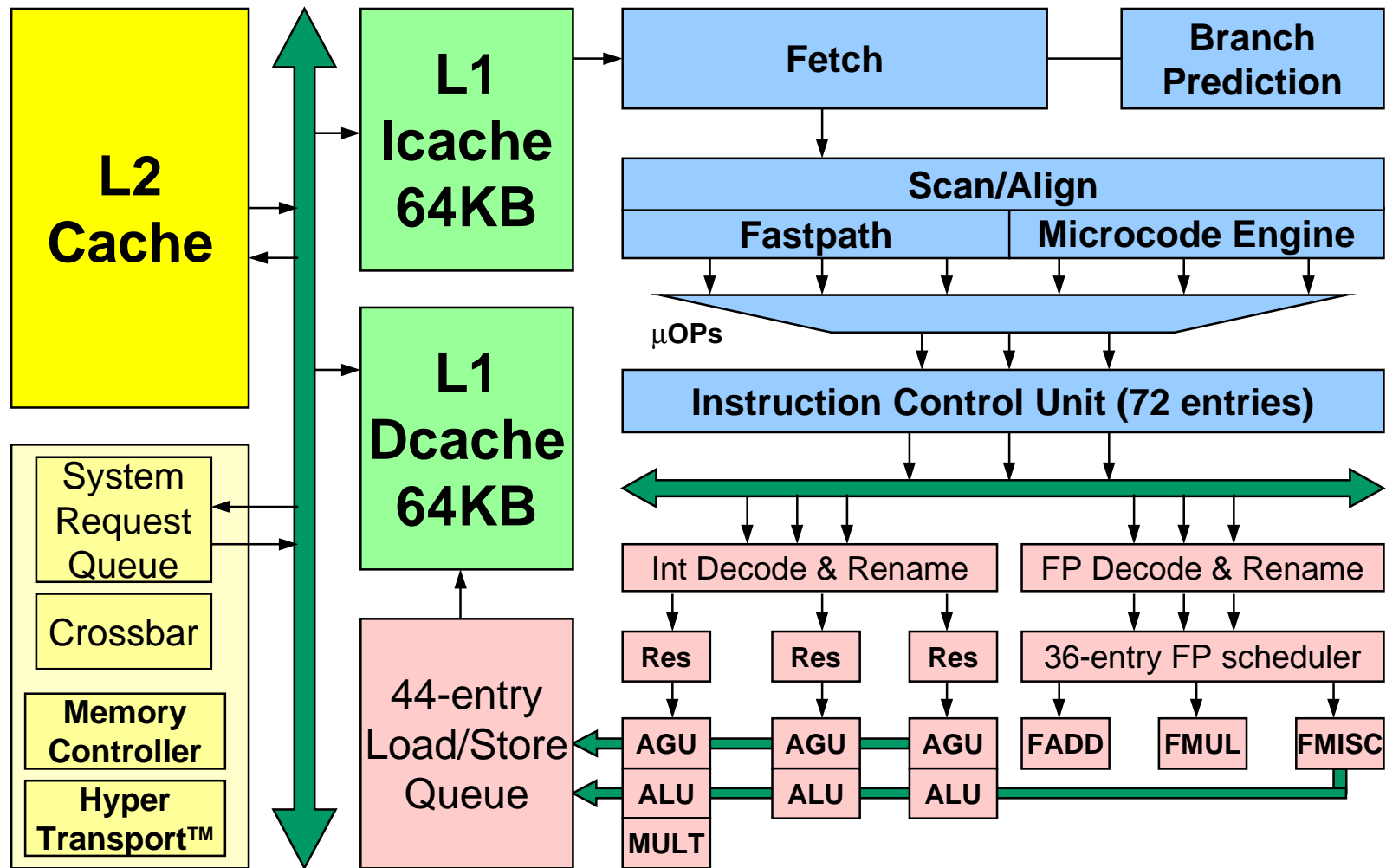
# Hammer Architecture Overview



- First x86-64 based processor
- Aggressive out-of-order, 9-issue superscalar processor
- Integrated DDR memory controller
- Leading performance in integer, floating point and multimedia
  - x86-64, x87, MMX™, 3DNow!™, SSE, SSE2



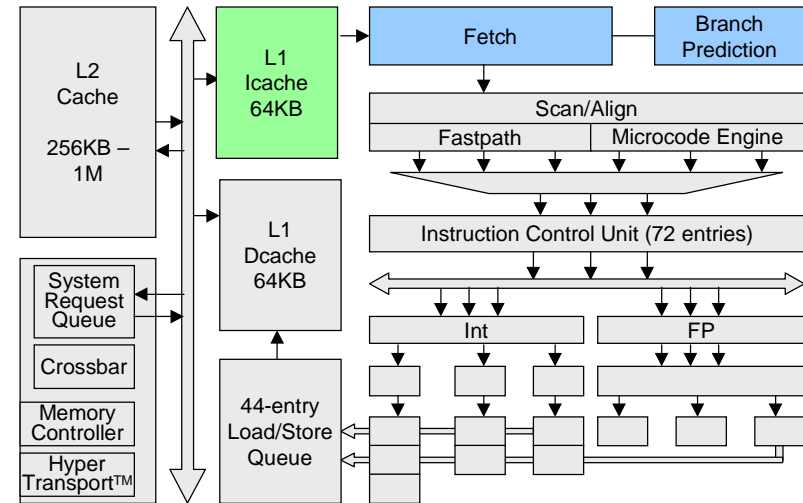
# Hammer Core Overview



# Instruction Fetch







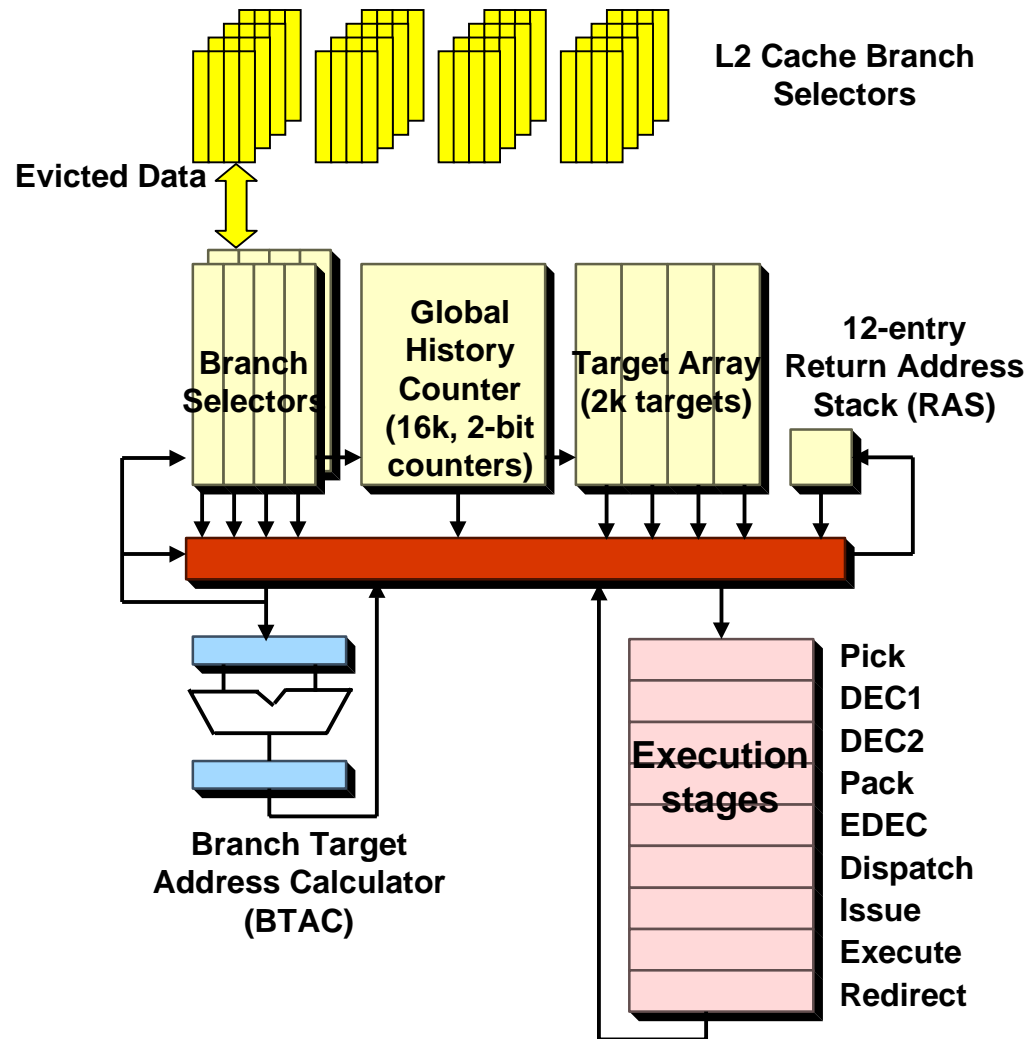
- Supply 16 instruction bytes to the decoder per cycle
- 64KB instruction cache, 2-way set associative
  - Linearly-indexed, physically-tagged, 64-byte block size
  - Prefetch next sequential block on a miss
- 2 sets of instruction cache tags (fetch port, snoop)
- Predecode instruction
  - 1 end bit per-byte
  - Decode some branch types
- Branch prediction



# Branch Prediction



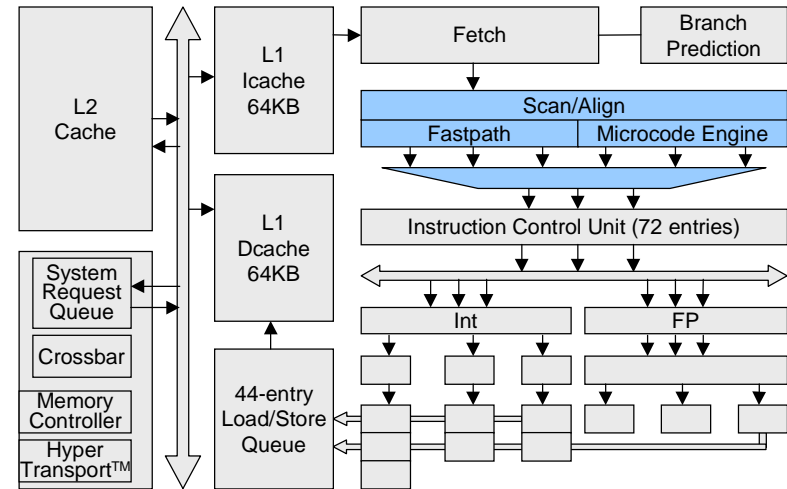
- Sequential Fetch  

- Predicted Fetch  

- Branch Target Address Calculator Fetch  

- Mispredicted Fetch  

- 5-10% improvement in prediction accuracy vs. AMD Athlon™



# Scan / Align



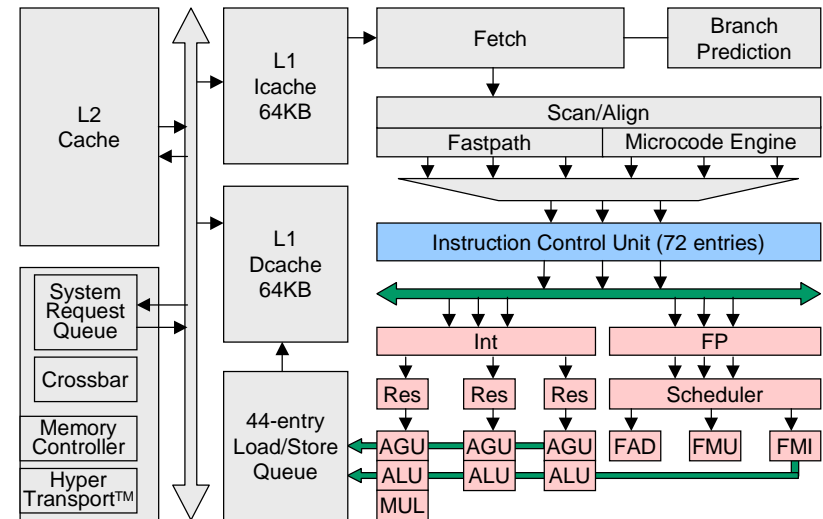
- Convert x86 instructions to fixed length  $\mu$ OPs
- Dispatch 3  $\mu$ OPs per cycle to integer/FP schedulers
- Instructions use one of two decoding pipelines
  - Fastpath: instructions decoding to two or fewer  $\mu$ OPs are decoded by hardware, packed into 3 dispatch positions
  - Microcode: x86 instructions decoding to more than two  $\mu$ OPs, calculate ROM entry point, fetch sequence from ROM
- Compared to AMD Athlon™, more instructions use the fastpath
  - Eg: Packed SSE is microcoded in AMD Athlon and fastpath in Hammer
  - Hammer has 8% fewer microcoded instructions for Specint2000
  - Hammer has 28% fewer microcoded instructions for Specfp2000



# Execution Units



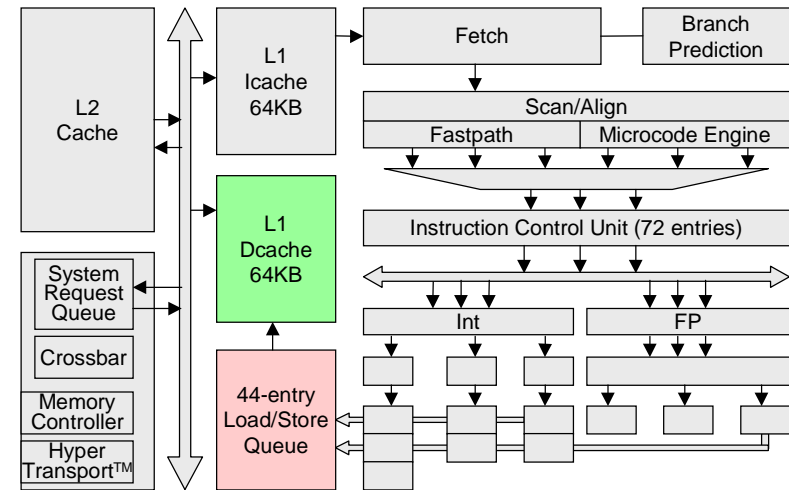
- 3 integer units
- 3 address generation units
- 3 superscalar floating point units
- Integer
  - Full 64-bit data path
  - 3 x 8-entry reservation stations
  - Single cycle 32 and 64-bit add, sub, rotate, shift, logical, etc.
  - 32-bit multiply: 3 cycle latency
  - 64-bit multiply: 5 cycle latency
- Floating point
  - Handles x87, MMX™, 3DNow!™, SSE and SSE2
  - 36-entry scheduler
  - Out-of-order, fully pipelined design



# Load/Store and Data Cache



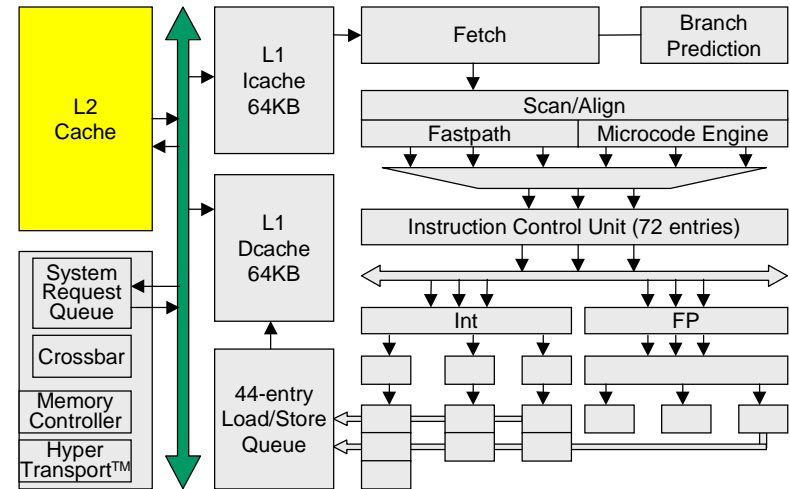
- 64KB data cache
  - 2-way set associative
  - Linearly-indexed, physically-tagged
  - 40-bit physical address
  - 48-bit linear address
  - MOESI coherency
  - 64-byte block size
- Banked and dual ported
  - 2 64-bit reads/writes each cycle to different banks
- 3 sets of data cache tags (port A, port B, snoop)
- Load->use latency is 3 cycles (zero segment base)
  - 1 extra cycle to handle misaligned (quadword boundary) loads
- Data forwarding from stores to dependent loads
- Hardware prefetch



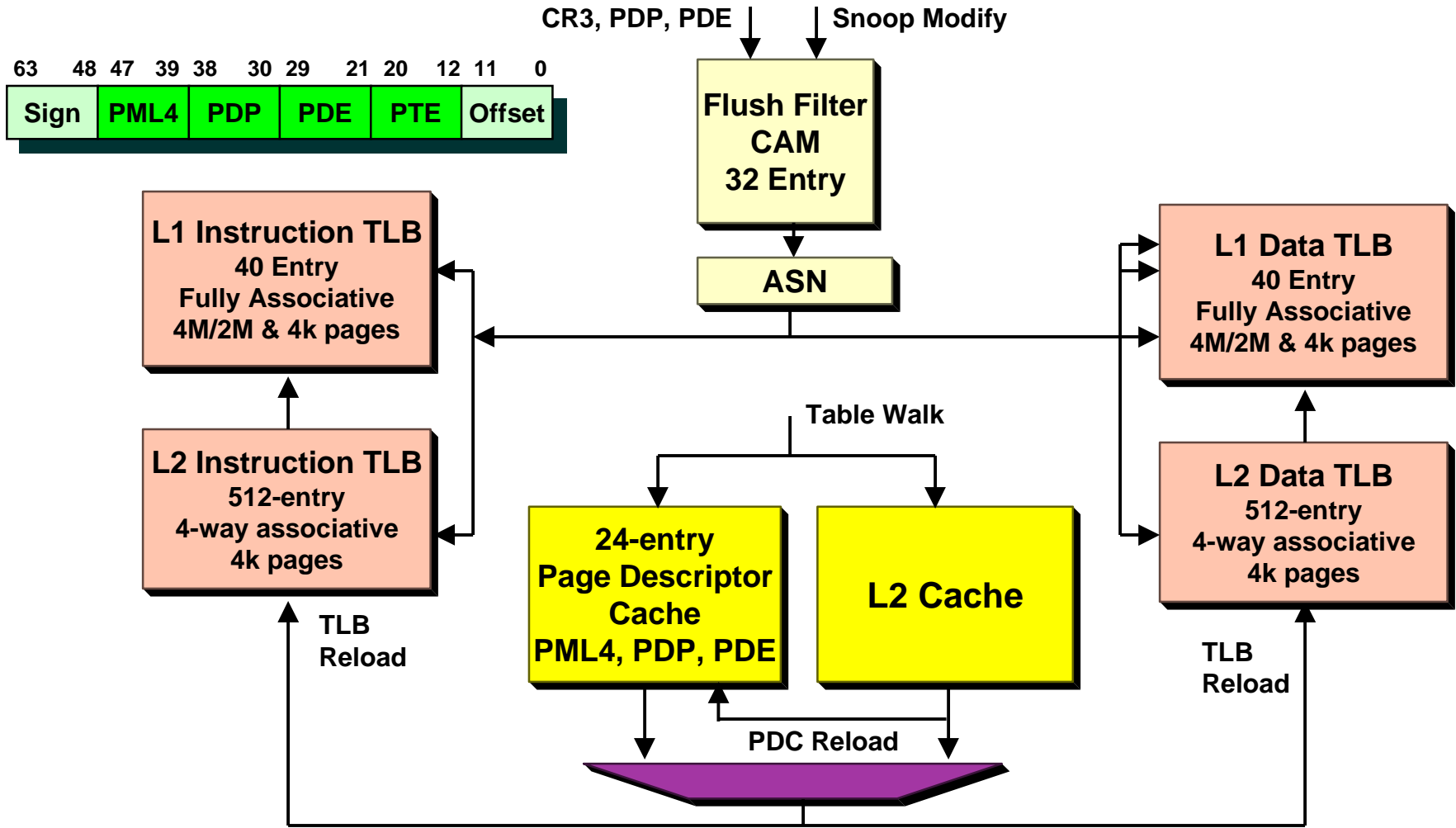
# L2 Cache



- Configurable sizes up to 1MB
- 16-way set associative
- L1 and L2 storage is mutually exclusive
- Pseudo-LRU scheme to reduce the number of LRU bits by half
- Stores IC predecode and branch prediction bits
- 10 outstanding miss requests
  - 8 DC
  - 2 IC
- System interface
  - Victim Buffer (8-entry)
  - Snoop Buffer (8-entry)
  - Write Buffer (4-entry)



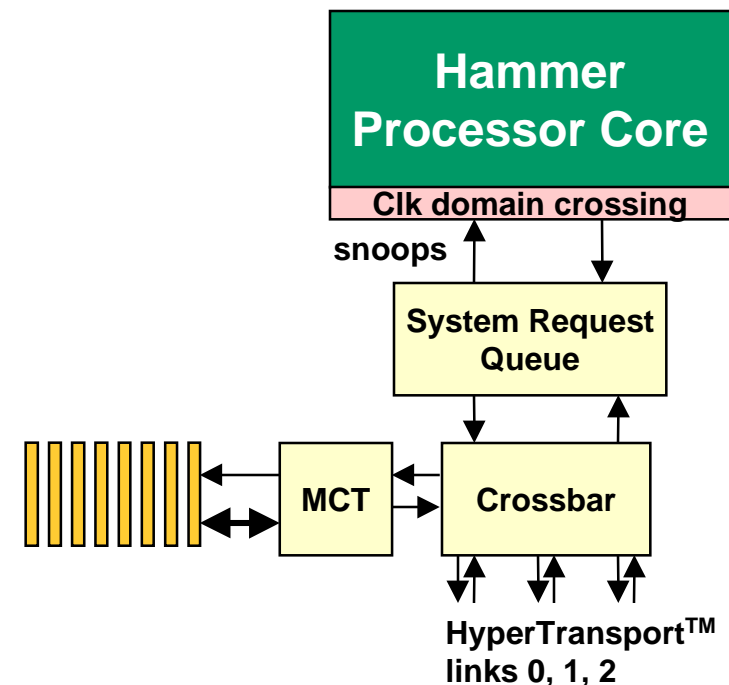
# TLB for Large Workloads



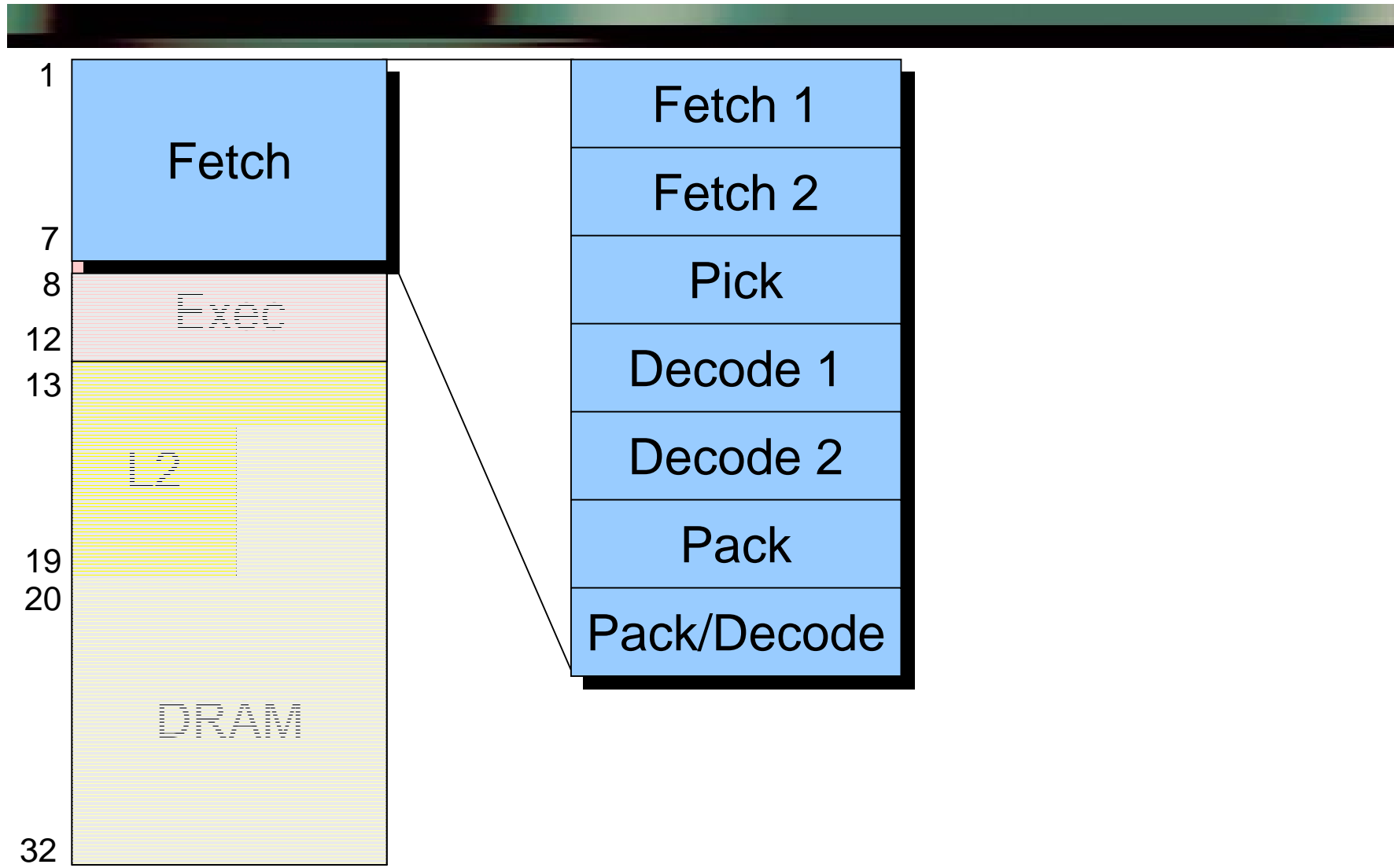
# Integrated Memory Controller



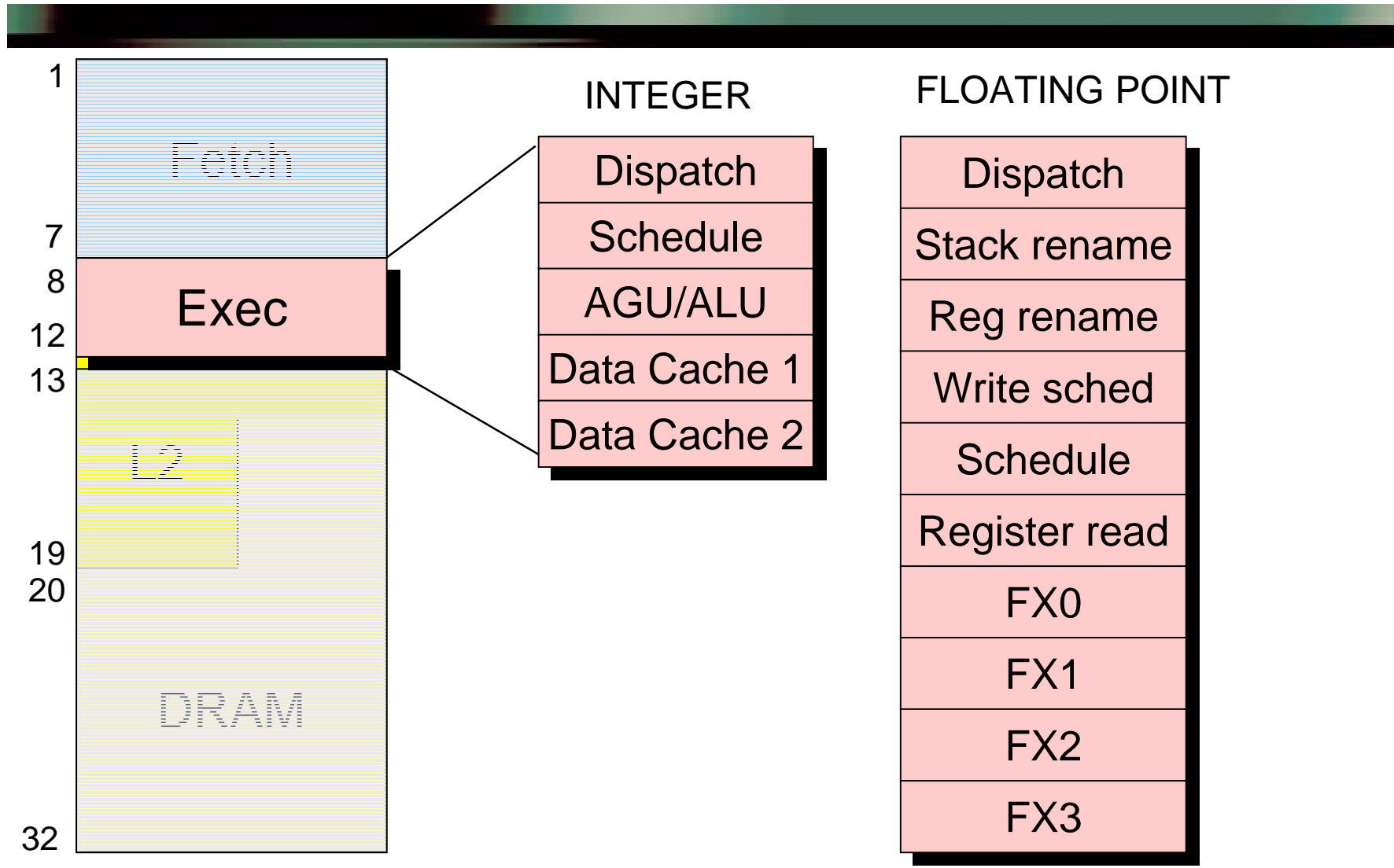
- Integrated DDR memory controller
  - 8-byte or 16-byte interface
  - Unbuffered or Registered DIMMs
  - 16-byte interface supports direct connection to 8 registered DIMMs and chipkill ECC
  - Significantly reduces memory latency
  - Memory latency improves as CPU and HyperTransport™ link speed improves
  - Performance improves by approximately 20% compared to AMD Athlon™ topology
  - Snoop throughput scales with CPU frequency
- Integrated Northbridge Functionality
  - Processes requests from CPU/IO to DRAM/IO
  - HyperTransport™ routing
    - peak bandwidth = 6.4GB/s
  - Handles transaction ordering and cache coherence
  - Runs at the same frequency as CPU core



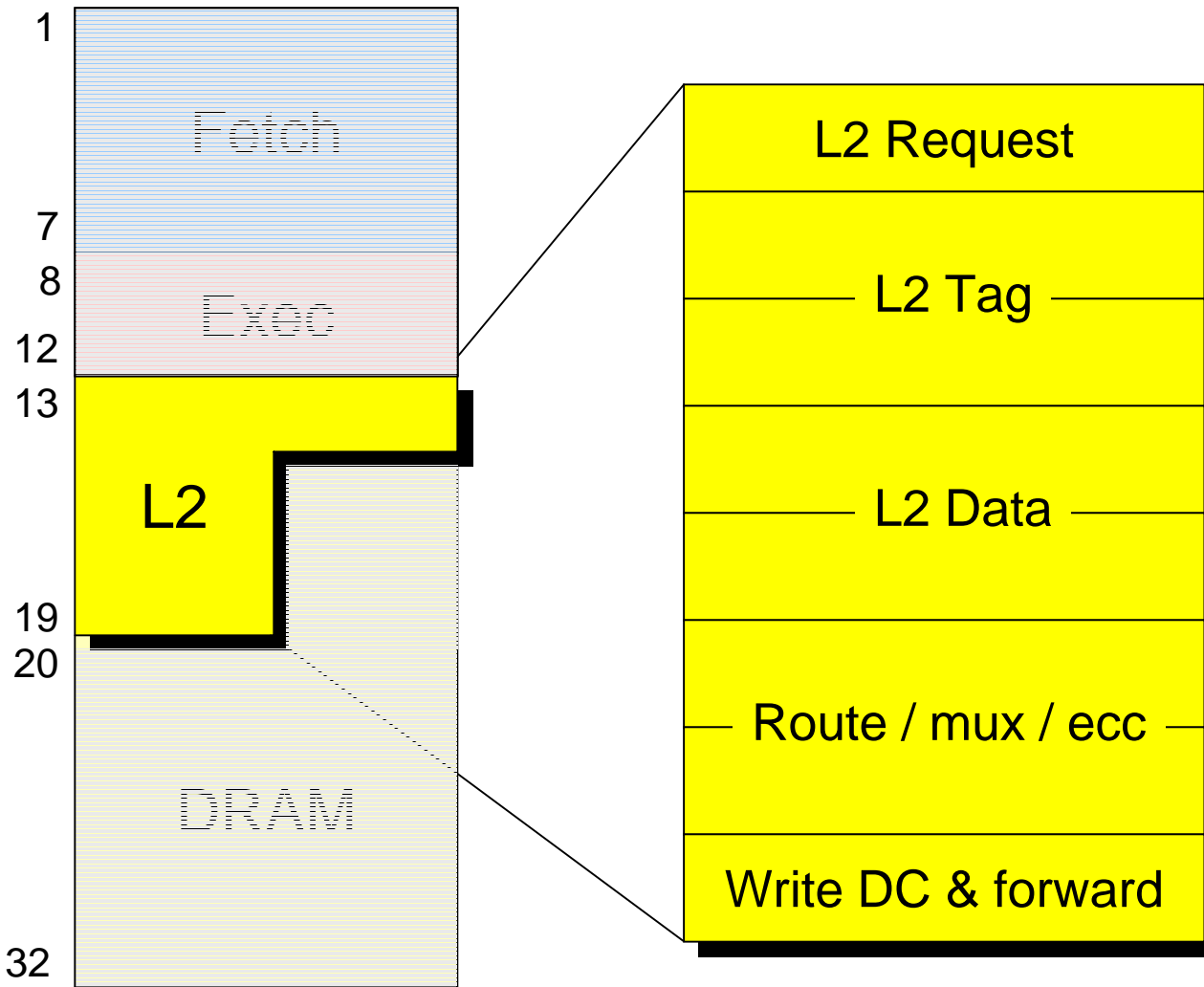
# Fetch/Decode Pipeline



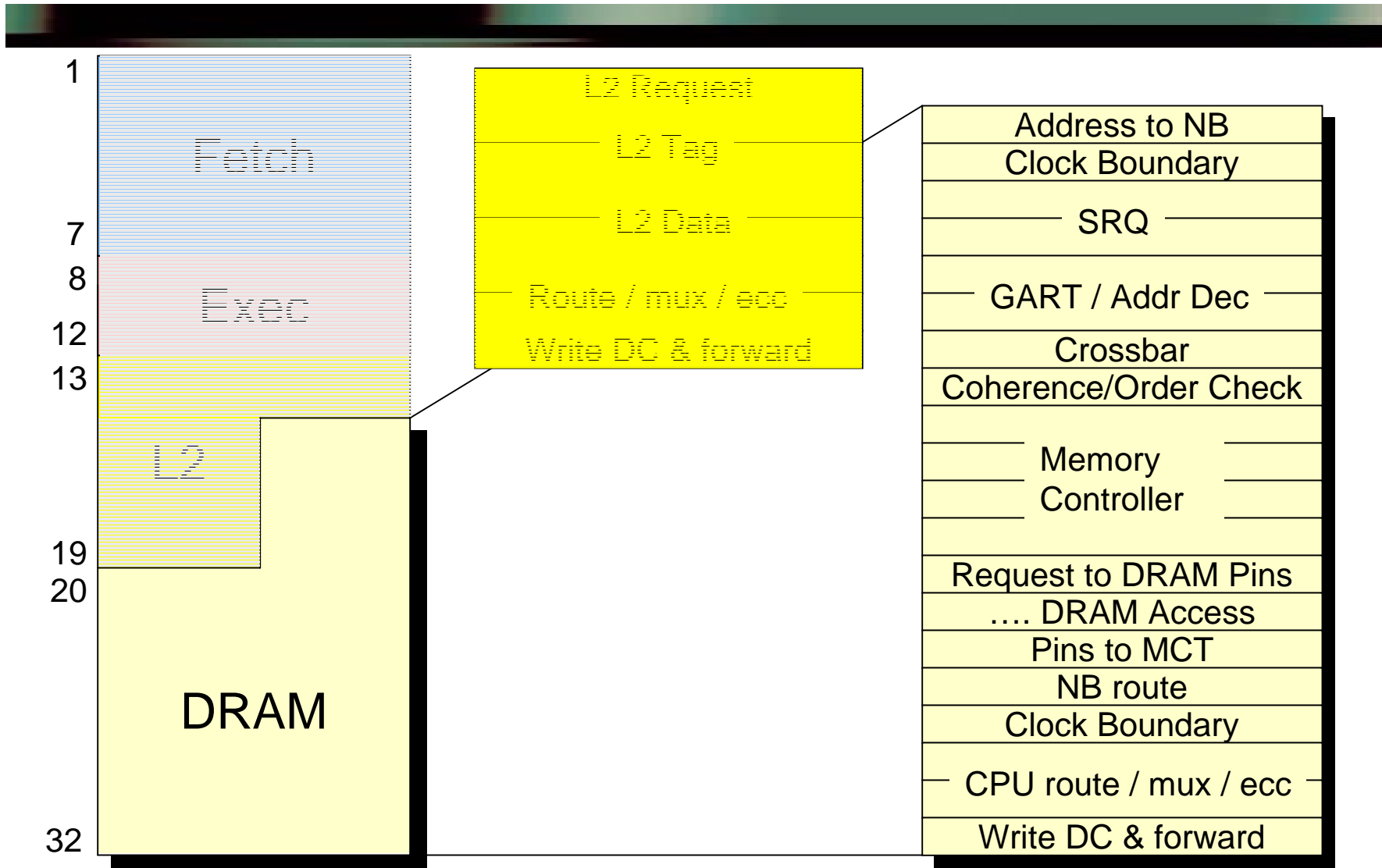
# Execute Pipeline



# L2 Pipeline



# DRAM Pipeline



# Reliability features



- L1 cache data is ECC protected
- L2 cache and tags are ECC protected
- DRAM is ECC protected with chipkill ECC support
- On-chip and off-chip ECC protected arrays include autonomous, background hardware scrubbers
- Remaining arrays are parity protected
  - Instruction cache, tags and TLBs
  - Data tags and TLBs
  - Generally read only data which can be recovered
- Machine Check Architecture
  - Report failures and predictive failure results

# Hammer Family of Processors



- Process Technology
  - 130nm SOI
  - 9-layer
  - copper interconnect
  - Dresden, Germany
- AMD Opteron™ with Hammer technology
  - 940 pin mPGA package
  - PC1600, PC2100, or PC2700 DDR memory
  - dual-channel DDR memory interface
  - Up to 3 HyperTransport™ links
    - 6.4GB/s each
    - 19.2GB/s aggregate
- AMD Athlon™ with Hammer technology
  - 754 pin mPGA package
  - PC1600, PC2100, or PC2700 DDR memory
  - Single-channel DDR memory interface
  - 1 HyperTransport™ link
    - 6.4GB/s

# Summary



- AMD's Hammer architecture provides a foundation for market-specific solutions:
  - Desktop, mobile, workstation (1-2 way), server (1-8 way)
- AMD's next-generation microprocessor core
  - Leading edge performance for 16-, 32- and 64-bit applications
- Cache subsystem
  - Enhanced TLB structures
  - Improved branch prediction
  - Reliability features
- Integrated DDR memory controller
  - Reduced memory latency
  - 1:1 scaling
- HyperTransport™ technology
  - Fast I/O for chip-to-chip communication
  - Enables glueless MP
- Innovation with compatibility

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